P.1/12

Chip Ferrite Bead BLM18□□□□□□N1□ Reference Specification

1.Scope

This reference specification applies to Chip Ferrite Bead BLM18_□N Series.

2.Part Numbering

(ex.) <u>BL</u> <u>M</u> <u>18</u> <u>AG</u> <u>121</u> <u>S</u> <u>N</u> <u>1</u> <u>D</u> (1) (2) (3) (4) (5) (6) (7) (8) (9)

(1)Product ID (2)Type (3)Dimension(LxW) (4)Characteristics (5)Typical Impedance at 100MHz

(6)Performance (7)Category (8)Numbers of Circuit (9)Packaging(D:Taping / B:Bulk)

3.Rating

					DC Resistance		
MURATA							
Part Number	resuring Condition		, (,				Remark
		Typical	at es°c		values		
DI MAODIZAGNAD			65 C	125 C		roomig	
	120±25%	120	2	00	0.25	0.35	
	220±25%	220	2	00	0.30	0.40	
							For
	470±25%	470	2	00	0.50	0.60	Digital
							Interface
	600±25%	600	2	00	0.60	0.70	
			1				
	1000±25%	1000	2	00	0.80	0.90	
		- }					
	20 min.	30	10	000	0.05	0.10	-
		33	33 3000*1			0.050	
	33±25%			1000*1	0.025		
				_			
	40 min.	60	10	000	0.1	0.2	
		120		I			
	120±25%		2000*1	1000*1 0.05	0.05	0.10	
	111	1					
······································	180±25%	180	1500*1	1000*1	0.09	0.18	
) 					
	220±25%	220	1400*1	1000*1	0.10	0.14	
	0,						-
	330±25%	330	1200*1	1000*1)*1 0.15	0.20	For DC
							power line
	470±25%	470	10	000	0.20	0.26	power line
	220±25%	220	2200*1	1500*1	0.050	0.060	
							1
	330±25%	330	1700*1	1200*1	0.080	0.095	
	470±25%	470	1500*	1000*1	0.130	0.145	
	000 + 070	000	4000*1	4000*1	0.450	0.407	
		600	1300*1	300*' 1000*'	0.150	0.165	
BLM18SD220SN1D	00.050/	22	0000*1	0500*1	0.000	0.013	
	22±25%		6000	3500 '	0.008		
BLM18SG330SN1D	00.070		*1	0=6-*1			
	33±25%	33	6000 '	3500	0.008	0.013	
	BLM18RK121SN1D BLM18RK121SN1B BLM18RK221SN1D BLM18RK221SN1D BLM18RK421SN1D BLM18RK471SN1D BLM18RK601SN1D BLM18RK601SN1D BLM18RK601SN1D BLM18RK102SN1D BLM18RK102SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG310SN1D BLM18PG310SN1D BLM18PG600SN1D BLM18PG600SN1D BLM18PG121SN1D BLM18PG121SN1D BLM18PG121SN1D BLM18PG121SN1D BLM18PG331SN1D BLM18PG331SN1D BLM18PG331SN1D BLM18PG331SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18KG221SN1D BLM18KG221SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG471SN1D BLM18KG601SN1D	MURATA Part Number (at 100MHz, Under St Testing Community Communit	Part Number	MURATA Part Number (at 100MHz, Under Standard Testing Condition) Curr (n BLM18RK121SN1D BLM18RK21SN1B BLM18RK221SN1B BLM18RK471SN1D BLM18RK471SN1D BLM18RK601SN1D BLM18RK601SN1D BLM18RK102SN1D BLM18RK102SN1D BLM18RK102SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG30SN1D BLM18PG121SN1D BLM18PG121SN1D BLM18PG121SN1D BLM18PG331SN1D BLM18PG471SN1D BLM18PG331SN1D BLM18RG331SN1D BLM18RG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG601SN1D BLM18KG	MURATA Part Number (at 100MHz, Under Standard Testing Condition) Current (mA) BLM18RK121SN1D BLM18RK221SN1B BLM18RK221SN1D BLM18RK221SN1D BLM18RK221SN1B BLM18RK471SN1D BLM18RK471SN1D BLM18RK471SN1D BLM18RK601SN1D BLM18RK601SN1D BLM18RK601SN1D BLM18RK102SN1D BLM18RK102SN1D BLM18RK102SN1D BLM18RK102SN1D BLM18RK102SN1D BLM18RK102SN1D BLM18RFG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG300SN1D BLM18PG30SN1D BLM18PG600SN1D BLM18PG600SN1D BLM18PG600SN1D BLM18PG6121SN1D BLM18PG6121SN1D BLM18PG6121SN1D BLM18PG121SN1D BLM18PG121SN1D BLM18PG221SN1D BLM18PG221SN1D BLM18PG221SN1D BLM18PG221SN1D BLM18PG221SN1D BLM18PG221SN1D BLM18PG331SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18PG331SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18PG471SN1D BLM18FG471SN1D BLM18FG471SN1D BLM18FG471SN1D BLM18KG221SN1D BLM18KG221SN1D BLM18KG221SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG331SN1D BLM18KG471SN1D BLM18KG471SN1B BLM18KG471S	MURATA Part Number	MURATA Part Number (at 100MHz, Under Standard Testing Condition) Current (mA) Initial (mA) Values After Testing Part Number (mA) Matter Testing Part Number (mA) After Testing Part Number (mA) After Testing Part Number (mA) After Testing BLM18RK221SN1B 120±25% 220 200 0.50 0.60 0.60 0.70 0.60 0.70 0.60 0.70 0.60 0.70 0.60 0.70 0.80 0.90 0.90 0.80 0.90 0.80 0.90 0.80 0.90 0.90 0.80 0.90 <td< td=""></td<>

Spec. No. JENF243A-0003Z-01

P.2/12

Spec. No. JENI 2		Impedance (Ω)	Rated	DC Resistance		F.2/12		
Customer	MURATA	(at 100MHz, Under Sta		Current	(Ω max.)		↓ .	
Part Number	Part Number	Testing Co	ondition)	(mA)	Initial	Values	Remark	
			Typical	at at 85°C 125°C	Values	After Testing	3	
	BLM18AG121SN1D	120±25%	120	800	0.18	0.28		
	BLM18AG121SN1B BLM18AG151SN1D							
	BLM18AG151SN1B	150±25%	150	700	0.25	0.35		
	BLM18AG221SN1D	000 050/	000	700	0.05	0.05	•	
	BLM18AG221SN1B	220±25%	220	700	0.25	0.35		
	BLM18AG331SN1D	330±25%	330	600	0.30	0.40	For general	
	BLM18AG331SN1B	33012370	330	000	0.50	0.40	use	
	BLM18AG471SN1D	470±25%	470	550	0.35	0.45		
	BLM18AG471SN1B							
	BLM18AG601SN1D BLM18AG601SN1B	600±25%	600	500	0.38	0.48		
	BLM18AG102SN1D							
	BLM18AG102SN1B	1000±25%	1000	450	0.50	0.60		
	BLM18BB050SN1D	F . 050/	<u> </u>	000	0.05	0.40		
	BLM18BB050SN1B	5±25%	5	800	0.05	0.10		
	BLM18BA050SN1D	5±25%	5	500	0.2	0.3		
	BLM18BA050SN1B	312370	3	300	0.2	0.0		
	BLM18BB100SN1D	10±25%	10	700	0.10	0.20		
	BLM18BB100SN1B		,	Z .				
	BLM18BA100SN1D BLM18BA100SN1B	10±25%	10	500	0.25	0.35		
	BLM18BB220SN1D		X	Y /				
	BLM18BB220SN1B	22±25%	22	700	0.20	0.30		
	BLM18BA220SN1D	22±25%	22	500	0.35	0.45		
	BLM18BA220SN1B	2212370	~ 22	300	0.55	0.40		
	BLM18BB470SN1D	47±25%	47	600	0.25	0.35		
	BLM18BB470SN1B BLM18BD470SN1D			(.				
	BLM18BD470SN1B	47±25%	47	500	0.3	0.4		
	BLM18BA470SN1D	4-10-04	1					
	BLM18BA470SN1B	47±25%	47	300	0.55	0.65		
	BLM18BB600SN1D	60±25%	60	600	0.25	0.35	For	
	BLM18BB600SN1B	0012370	- 00	000	0.20	0.00	high speed	
	BLM18BA750SN1D	75±25%	75	300	0.70	0.80	signal line	
	BLM18BA750SN1B BLM18BB750SN1D							
	BLM18BB750SN1B	75±25%	75	600	0.30	0.40		
	BLM18BB121SN1D	400 07-1	40-			6.15		
	BLM18BB121SN1B	120±25%	120	550	0.30	0.40		
	BLM18BD121SN1D	120±25%	120	300	0.4	0.5		
	BLM18BD121SN1B	120520/0	120	300	0.4	0.0		
	BLM18BA121SN1D	120±25%	120	200	0.9	1.0		
	BLM18BA121SN1B				1			
	BLM18BB141SN1D BLM18BB141SN1B	140±25%	140	500	0.35	0.45		
	BLM18BB151SN1D					_		
	BLM18BB151SN1B	150±25%	150	450	0.37	0.47		
	BLM18BD151SN1D	150:050/	150	200	0.4	0.5	1	
	BLM18BD151SN1B	150±25%	150	300	0.4	0.5		
	BLM18BB221SN1D	220±25%	220	450	0.45	0.55		
	BLM18BB221SN1B				0.40	0.00		
	BLM18BD221SN1D	220±25%	220	250	0.45	0.55		
	BLM18BD221SN1B		<u> </u>		l	1		

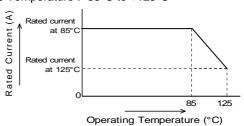
D		11	2
г	. 3/	'	_

		Impedance (Ω) (at 100MHz, Under Standard		Rated Current		DC Resistance (Ω max.)		
Customer	MURATA						Values	Remark
Part Number	Part Number	Ü		at lat		Values	After Testing	. remain
	BLM18BB331SN1D BLM18BB331SN1B	330±25%	330	400		0.58	0.68	
	BLM18BD331SN1D BLM18BD331SN1B	330±25%	330	2	50	0.5	0.6	
	BLM18BD421SN1D BLM18BD421SN1B	420±25%	420	2	50	0.55	0.65	
	BLM18BB471SN1D	470±25%	470	3	00	0.85	0.95	
	BLM18BB471SN1B BLM18BD471SN1D	470±25%	470	2	50	0.55	0.65	
	BLM18BD471SN1B BLM18BD601SN1D							
	BLM18BD601SN1B BLM18BD102SN1D	600±25%	600	2	00	0.65	0.75	
	BLM18BD102SN1B	1000±25%	1000	2	00	0.85	0.95	
	BLM18BD152SN1D BLM18BD152SN1B	1500 <u>±2</u> 5%	1500	1	50	1.2	1.3	
	BLM18BD182SN1D BLM18BD182SN1B	1800 <u>±25</u> %	1800	1	50	1.5	1.6	
	BLM18BD222SN1D BLM18BD222SN1B	2200±25%	2200		50	1.5	1.6	
	BLM18BD252SN1D	2500±25%	2500	1	50	1.5	1.6	
	BLM18BD252SN1B BLM18TG121TN1D	120±25%	120	2	00	0.25	0.3	
	BLM18TG121TN1B BLM18TG221TN1D	220±25%	220		00	0.3	0.4	
	BLM18TG221TN1B BLM18TG601TN1D		•	(:				
	BLM18TG601TN1B	600±25%	600	100		0.45	0.6	
	BLM18TG102TN1D BLM18TG102TN1B	1000±2 <mark>5</mark> %	1000			0.6	0.8	
	BLM18SG260TN1D BLM18SG260TN1B	26±25%	26	6000*1	1000*1	0.007	0.012	
	BLM18SG700TN1D BLM18SG700TN1B	70±25%	70	4000*1	1000*1	0.020	0.030	
	BLM18SG121TN1D BLM18SG121TN1B	120±25%	120	3000*1	1000*1	0.025	0.035	
	BLM18SG221TN1D BLM18SG221TN1B	220±25%	220	2500*1	1000*1	0.040	0.055	
	BLM18SG331TN1D BLM18SG331TN1B	330±25%	330	1500*1	1000*1	0.070	0.085	
	BLM18SN220TN1D BLM18SN220TN1B	22±7	22	8000*1	5000*1	0.004	0.005	For DC power line
	BLM18KG260TN1D	26±25%	26	6000*1	4000*1	0.007	0.012	(Thin type)
	BLM18KG260TN1B BLM18KG300TN1D	30±25%	30			0.010	0.015	
	BLM18KG300TN1B BLM18KG700TN1D	70±25%	70	3500°1	2200*1	0.010	0.013	
	BLM18KG700TN1B BLM18KG101TN1D							
	BLM18KG101TN1B BLM18KG121TN1D	100±25%	100	3000*1	1900*1	0.030	0.040	
	BLM18KG121TN1B	120±25%	120	3000*1	1900*1	0.030	0.040	

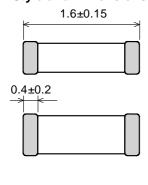
Spec. No. JENF243A-0003Z-01

• Operating Temperature : -55°C to +125°C • Storage Temperature : -55°C to +125°C

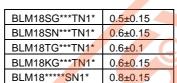
(*1)In case of Rated current is more than 1A, Rated Current is derated as right figure depending on the operating temperature.



4. Style and Dimensions







: Electrode

■ Equivalent Circuit



Resistance element becomes dominant at high frequencies.

■ Unit Mass (Typical value) BLM18*****SN1*:0.005g BLM18*****TN1*:0.004g

(in mm)

5.Marking

No marking.

6.Standard Testing Conditions

< Unless otherwise specified >

Temperature : Ordinary Temp. (15 °C to 35 °C)
Humidity : Ordinary Humidity (25%(RH) to 85%(RH))

< In case of doubt >

Temperature : 20°C±2 °C Humidity : 60%(RH) to 70%(RH)

Atmospheric pressure: 86kPa to 106kPa

7.Specifications

7-1. Electrical Performance

No.	Item	Specification	Test Method
7-1-1	Impedance	Meet item 3.	Measuring Frequency: 100MHz±1MHz Measuring Equipment: Agilent 4291A or the equivalent Test Fixture: Agilent 16192A or the equivalent
7-1-2	DC Resistance	Meet item 3.	Measuring Equipment : Digital multi meter For BLM18SN_TN Measuring Equipment : YOKOGAWA 755611 or the equivalent Test Fixture : Agilent 16044A or the equivalent *Except resistance of the Substrate and Wire

MURATA MFG.CO., LTD.

P.4/12

P.5/12

7-2.Mechanical Performance

No.	echanical Pe Item	1	ification	Test Method
7-2-1	Appearance	Meet item 4.		Visual Inspection and measured with Slide Calipers.
	and Dimensions			
7-2-2	Bonding	Meet Table 1		It shall be soldered on the substrate.
	Strength			Applying Force(F): 6.8N
		Table 1	·	Applying Time: 5s±1s
		Appearance	No damage	Applied direction :Parallel to substrate Side view
		Impedance	Within ±30%	
		Change	(for	R0.5 🕌 👢
		(at 100MHz)	BLM18SN	
			Within	
		DC	±50%)	Substrate
		Resistance	Meet item 3.	
7-2-3	Bending			It shall be soldered on the substrate.
	Strength			Substrate: Glass-epoxy 100mm×40mm×1.6mm Deflection: 1.0mm
				Speed of Applying Force: 0.5mm/s Pressure jig
				Keening Time: 30s
				R340 F
				Deflection
				45mm 45mm Product
				~ \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\
7-2-4	Vibration			It shall be soldered on the substrate.
-	Vibration			Oscillation Frequency: 10Hz to 55Hz to 10Hz for 1 min
				Total Amplitude: 1.5mm
				Testing Time: A period of 2 hours in each of 3 mutually
7 2 5	Decistones	Meet Table 2		perpendicular directions. (Total 6 h) Pre-Heating: 150°C±10°C, 60s~90s
7-2-5	Resistance to Soldering	Meet Table 2	· • • • • • • • • • • • • • • • • • • •	Solder: Sn-3.0Ag-0.5Cu
	Heat	Table 2	1)	Solder Temperature : 270°C±5°C
		Appearance	No damage	Immersion Time : 10s±0.5s
		Impedance	Within ±30%	Immersion and emersion rates : 25mm/s
		Change	(for BLM18KG	Then measured after exposure in the room condition for 48h±4h.
		(at 100MHz)	Within ±40%)	
			(for BLM18SN	
			Within ±50%)	
		DC	Meet item 3.	
		Resistance		
7-2-6	Drop		l be no failure	It shall be dropped on concrete or steel board.
		after tested.		Method : free fall
				Height: 75cm Attitude from which the product is dropped: 3 direction
				The number of times: 3 times for each direction(Total 9 times)
7-2-7	Solderability	The electrode	es shall be at	Flux: Ethanol solution of rosin,25(wt)%
	,	least 95% cov	vered with new	Pre-Heating : 150°C±10°C, 60s~90s
		solder coating	l .	Solder : Sn-3.0Ag-0.5Cu
				Solder Temperature : 240°C±5°C
				Immersion Time : 3s±1s Immersion and emersion rates : 25mm/s
I				minicision and emersion fales . Zomin/S

P.6/12

7-3. Environmental Performance

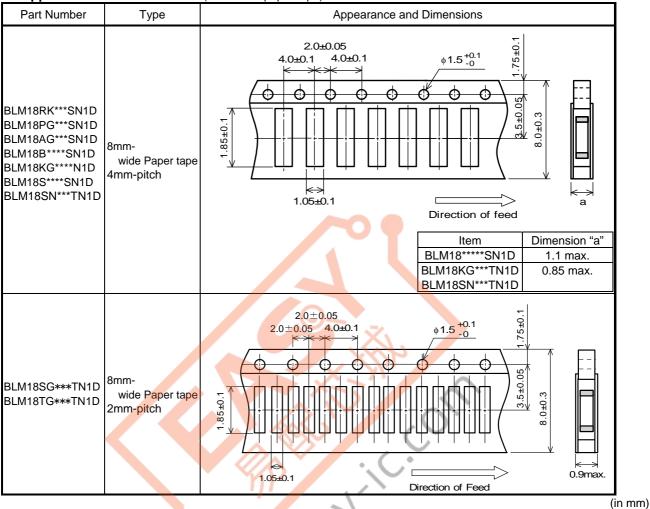
It shall be soldered on the substrate.

No.	Item	Speci	fication	Test Method				
	Temperature	Meet Table 3.		1 cycle:				
	Cycle			1 step:-55 °C(+0 °C,-3 °C) / 30min±3min				
		Table 3	Т	2 step:Ordinary temp. / 10min to 15min				
		Appearance	No damage	3 step:+125 °C(+3 °C,-0 °C) / 30min±3min				
		Impedance	Within ±30%	4 step: Ordinary temp. / 10min to 15min Total of 100 cycles				
		Change	(for BLM18KG	Then measured after exposure in the room condition for 48h±4h.				
		(at 100MHz)	Within-10%to	Then medicated after expectate in the reem contained for ten 2 m.				
			+50%)					
			(for BLM18SN					
		DO.	Within ±50%)					
		DC Resistance	Meet item 3.					
7-3-2	Humidity	Meet Table 1.		Temperature : 40°C±2°C				
				Humidity: 90%(RH) to 95%(RH)				
				Time: 1000h(+48h,-0h)				
7-3-3	Heat Life			Then measured after exposure in the room condition for 48h±4h. Temperature: 125°C±3°C				
7-3-3	rieat Life			(in case of Rated current is more than 1A,				
				do the test at : +85 °C±3°C)				
				Applying Current : Rated Current				
				Time: 1000h(+48h,-0h)				
				Then measured after exposure in the room condition for 48h±4h.				
7-3-4	Cold			Temperature: -55±2°C				
	Resistance			Time: 1000h(+48h,-0h)				
	Then measured after exposure in the room condition for 48h±4h.							



8. Specification of Packaging

8-1.Appearance and Dimensions (8mm-wide paper tape)



(1) Taping

Products shall be packaged in the cavity of the base tape continuously and sealed by top tape and bottom tape.

- (2) Sprocket hole: The sprocket holes are to the right as the tape is pulled toward the user.
- (3) Spliced point: The base tape and top tape have no spliced point
- (4) Cavity: There shall not be burr in the cavity.
- (5) Missing components number

Missing components number within 0.1% of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

8-2. Tape Strength

(1)Pull Strength

Top tape

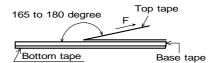
Bottom tape

5N min.

(2)Peeling off force of Top tape

0.1N to 0.6N (Minimum value is typical.)

*Speed of Peeling off:300mm/min



8-3. Taping Condition

(1)Standard quantity per reel

Type	Quantity per 180mm reel
BLM18(except BLM18SG/BLM18TG)	4000 pcs. / reel
BLM18SG/BLM18TG	10000 pcs. / reel

- (2)There shall be leader-tape (top tape and empty tape) and trailer- tape (empty tape) as follows.
- (3)On paper tape, the top tape and the base tape shall not be adhered at the tip of the empty leader tape for more than 5 pitch.

(4)Marking for reel

The following items shall be marked on a label and the label is stuck on the reel.

(Customer part number, MURATA part number, Inspection number(*1), RoHS Marking(*2), Quantity, etc)

*1) « Expression of Inspection No. »

 $\Box\Box$ OOOO $\times\times$

(1) Factory Code

(2) Date First dig

First digit : Year / Last digit of year

Second digit : Month / Jan. to Sep. \rightarrow 1 to 9, Oct. to Dec. \rightarrow O, N, D

Third, Fourth digit: Day

(3) Serial No.

*2) « Expression of RoHS Marking »

ROHS $-\frac{Y}{(1)}(\underline{\Delta})$

- (1) RoHS regulation conformity parts.
- (2) MURATA classification number

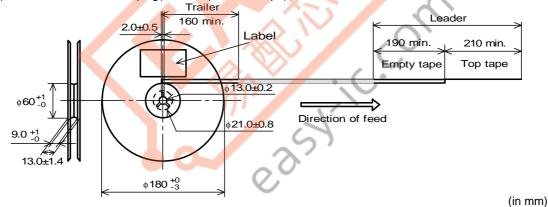
(5)Outside package

These reels shall be packed in the corrugated cardboard package and the following items shall be marked on a label and the label is stuck on the box.

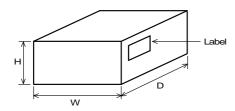
(Customer name, Purchasing order number, Customer part number, MURATA part number,

RoHS discrimination(*2), Quantity, etc)

(6) Dimensions of reel and taping (leader-tape, trailer-tape)



8-4. Specification of Outer Case



Outer Case Dimensions (mm)			Standard Reel Quantity in Outer Case
W	D	Н	(Reel)
186	186	93	5

^{*} Above Outer Case size is typical. It depends on a quantity of an order.

Spec. No. JENF243A-0003Z-01

9. 🗘 Caution

9-1.Surge current

Excessive surge current (pulse current or rush current) than specified rated current applied to the product may cause a critical failure, such as an open circuit, burnout caused by excessive temperature rise.

Please contact us in advance in case of applying the surge current.

9-2.Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (6) Disaster prevention / crime prevention equipment
- (2) Aerospace equipment
- (7) Traffic signal equipment
- (3) Undersea equipment
- (8) Transportation equipment (vehicles,trains,ships,etc.)
- (4) Power plant control equipment
- (9) Applications of similar complexity and /or reliability requirements to the applications listed in the above
- (5) Medical equipment to the application

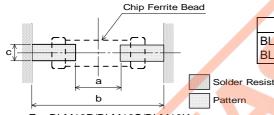
10. Notice

This product is designed for solder mounting.

Please consult us in advance for applying other mounting method such as conductive adhesive.

10-1.Land pattern designing

- Standard land dimensions
- < For BLM18 series (except BLM18P/BLM18S/BLM18K type) >

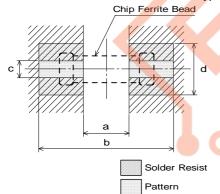


Туре	Soldering	а	b	С
BLM18 (except18P/18S/	Flow	0.7	2.2 to 2.6	0.7
BLM18K type)	Reflow	0.7	1.8 to 2.0	0.7

(in mm)

P.9/12

< For BLM18P/BLM18S/BLM18K type >



	Type	Rated Current	а	b	С		paa tnic dimens	
		(A)				18µm	35µm	70µm
	BLM18P	0.5 to 1.5)	Flow		0.7	0.7	0.7
1	BLM18P BLM18S	1.7 to 2.5	0.7	2.2 to 2.6	0.7	1.2	0.7	0.7
4	BLM18K	3 to 4	0.7	Reflow	_	2.4	1.2	0.7
	DEWITOR	5 to 6		1.8 to 2.0		6.4	3.3	1.65
	BLM18SN	8	0.7	2.0	0.7	-	6.4	3.3
		*						

(in mm)

10-2. Soldering Conditions

Products can be applied to reflow and flow soldering.

(1) Flux, Solder

Flux	Use rosin-based flux, but not highly acidic flux (with chlorine content exceeding 0.2(wt)%.) Do not use water-soluble flux.
Solder	Use Sn-3.0Ag-0.5Cu solder Standard thickness of solder paste : 100 μm to 200 μm

(2) Soldering conditions

• Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.

Insufficient pre-heating may cause cracks on the ferrite, resulting in the deterioration of product quality.

• Standard soldering profile and the limit soldering profile is as follows.

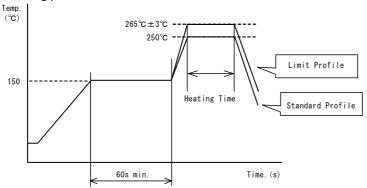
The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.

^{*}The excessive heat by land pads may cause deterioration at joint of products with substrate.

P.10/12

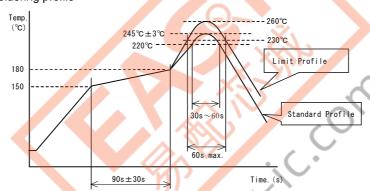
(3) soldering profile

☐Flow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150°C、60s min.	
Heating	250°C、4∼6s	265°C±3°C, 5s max.
Cycle of flow	2 times	2 times

☐Reflow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150~180°C 、90s±30s	2
Heating	above 220°C、30s~60s	above 217°C、60s~150s
Peak temperature	245±3°C	260°C,10s
Cycle of reflow	2 times	2 times

10-3. Reworking with soldering iron

• Pre-heating: 150°C, 1 min

• Soldering iron output: 80W max.

• Tip temperature: 350°C max.

• Tip diameter: ϕ 3mm max.

• Soldering time : 3(+1,-0) seconds.

• Times : 2times max.

Note :Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

10-4.Solder Volume

Solder shall be used not to be exceeded as shown below.



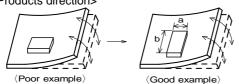
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.



10-5. Attention regarding P.C.B. bending

The following shall be considered when designing and laying out P.C.B.'s.

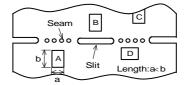
(1) P.C.B. shall be designed so that products are not subject to the mechanical stress for board warpage. <Products direction>



Products shall be located in the sideways direction (Length: a<b) to the mechanical stress.

(2)Products location on P.C.B. separation. Products (A, B, C, D) shall be located carefully so that products are not subject to the mechanical stress due to warping the board. Because they may be subjected the mechanical

stress in order of A>C>B \cong D.



10-6. Mounting density

Add special attention to radiating heat of products when mounting the inductor near the products with heating. The excessive heat by other products may cause deterioration at joint of this product with substrate.

10-7. Operating Environment

Do not use this product under the following environmental conditions, on deterioration of the Insulation Resistance of the Ferrite material and/or corrosion of Inner Electrode may result from the use.

- (1) in the corrodible atmosphere (acidic gases, alkaline gases, chlorine, sulfur gases, organic gases and etc.)
- (2) in the atmosphere where liquid such as organic solvent, may splash on the products
- (3) in the atmosphere where the temperature / humidity changes rapidly and it is easy to dew

10-8. Resin coating

The impedance value may change and/or it may affect on the product's performance due to high cure-stress of resin to be used for coating / molding products. So please pay your careful attention when you select resin. In prior to use, please make the reliability evaluation with the product mounted in your application set.

10-9. Cleaning Conditions

Products shall be cleaned on the following conditions.

- (1)Cleaning temperature shall be limited to 60°C max. (40°C max. for IPA.)
- (2)Ultrasonic cleaning shall comply with the following conditions, avoiding the resonance phenomenon at the mounted products and P.C.B.

Power:20W/ℓ max. Frequency:28kHz to 40kHz Time:5 min max.

(3)Cleaner

- 1.Alternative cleaner
 - •Isopropyl alcohol (IPA)
- 2.Aqueous agent
 - •PINE ALPHA ST-100S
- (4) There shall be no residual flux and residual cleaner after cleaning.

In the case of using aqueous agent, products shall be dried completely after rinse with de-ionized water in order to remove the cleaner.

(5)Other cleaning

Please contact us.



Spec. No. JENF243A-0003Z-01

P.12/12

10-10. Handling of a substrate

After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.

Excessive mechanical stress may cause cracking in the product.

Bending

Twisting



10-11. Storage Conditions

(1)Storage period

Use the products within 6 months after delivered.

Solderability should be checked if this period is exceeded.

(2)Storage conditions

• Products should be stored in the warehouse on the following conditions.

Temperature: -10°C to 40°C

Humidity : 15% to 85% relative humidity
No rapid change on temperature and humidity

- Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization
 of electrode, resulting in poor solderability.
- Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
- Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be stored under the airtight packaged condition.

(3)Delivery

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

11 . 1 Note

- (1)Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2) You are requested not to use our product deviating from the reference specifications.
- (3) The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering.